

Title (en)

METHOD FOR PRODUCTION OF A COMPONENT WITH A MICRO-JOINT AND COMPONENT PRODUCED BY SAID METHOD

Title (de)

HERSTELLUNGSVERFAHREN EINES BAUELEMENTS, DAS EINE MIKROVERBINDUNG ENTHÄLT, UND DURCH SOLCHES VERFAHREN HERGESTELLTES BAUELEMENT

Title (fr)

PROCEDE DE REALISATION D'UN COMPOSANT COMPORTANT UN MICRO-JOINT ET COMPOSANT REALISE PAR CE PROCEDE

Publication

**EP 1558518 A2 20050803 (FR)**

Application

**EP 03767900 A 20031104**

Priority

- FR 0303288 W 20031104
- FR 0213998 A 20021108

Abstract (en)

[origin: FR2846906A1] The production of a component, incorporating a micro-structure substrate (3) and a complementary element is assembled via an assembly joint. The assembly joint is fabricated by: (a) deposition on a transfer substrate (1) of a thin polymer film (2), the transfer substrate and the polymer film having a predetermined chemical affinity; (b) putting the micro-structure substrate in contact with the polymer film, the micro-structure substrate and the polymer film having a chemical affinity greater than that between the transfer substrate and the polymer film; (c) withdrawal of the transfer substrate so that the assembly joint is formed by the zones of the polymer film coming into contact with the micro-structure. An Independent claim is also included for a component obtained by this method where the complementary element is a casing or another micro-structure substrate or a capillary or matrix of capillaries.

IPC 1-7

**B81C 1/00**; **B32B 31/24**

IPC 8 full level

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CPC (source: EP US)

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